

PRODUCT / PROCESS CHANGE NOTIFICATION

1. PCN basic data

1.1 Company	 STMicroelectronics International N.V
1.2 PCN No.	EMBEDDED PROCESSING/26/16266
1.3 Title of PCN	HTXA (China) additional UFQFPN5x5 32L and UFQFPN7x7 48L package assembly line for STM32G03x/G04x, STM32G05x/G07x and STM32G08x listed products
1.4 Product Category	STM32G031x, STM32G041x, STM32G051x, STM32G071x and STM32G081x.
1.5 Issue date	2026-07-15

2. PCN Team

2.1 Contact supplier	
2.1.1 Name	PIKE EMMA
2.1.2 Phone	+44 1628896111
2.1.3 Email	emma.pike@st.com
2.2 Change responsibility	
2.2.1 Product Manager	Patrick AIDOUNE
2.1.2 Marketing Manager	Marie TOURNUT
2.1.3 Quality Manager	Pascal NARCHE

3. Change

3.1 Category	3.2 Type of change	3.3 Manufacturing Location
Transfer	Line transfer for a full process or process brick (process step, control plan, recipes) from one site to another site: Assembly site (SOP 2617)	HTXA (China)

4. Description of change

	Old	New
4.1 Description	Assembly lines : - ST Calamba (Philippines) - ASE KaoHsiung (Taiwan) - StatsChipPAC JSCC Jiangyin (China)	Assembly lines : - ST Calamba (Philippines) - ASE KaoHsiung (Taiwan) - StatsChipPAC JSCC Jiangyin (China) and - HTXA (China) - new additional line
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	no impact on form, Fit, Function	

5. Reason / motivation for change

5.1 Motivation	Due to the success on the market of STM32 devices, ST General Purpose and Automotive Microcontrollers division decided to qualify an additional back-end site to maintain state of the art service level to our customers thanks to extra capacity.
5.2 Customer Benefit	SERVICE IMPROVEMENT

6. Marking of parts / traceability of change

6.1 Description	Change is visible on the marking Assembly Site code . - 78: ST Calamba (Philippines) - AA : ASE KaoHsiung (Taiwan) - GQ : STATSChipPAC JSCC JiangYing (China) - GU: HTXA (China) Please refer to PCN 16266_Aadditional information.pdf document for further details.
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7. Timing / schedule

7.1 Date of qualification results	2026-09-20
7.2 Intended start of delivery	2026-09-20
7.3 Qualification sample available?	Upon Request

8. Qualification / Validation			
8.1 Description	16266 MDRF-GPAM RER2611 PCN16266_ HTXA QFN7x7 & 5x5 CuPd wires - reliability evaluation plan.pdf		
8.2 Qualification report and qualification results	Available (see attachment)	Issue Date	2026-07-15

9. Attachments (additional documentations)	
16266 Public product.pdf 16266 MDRF-GPAM RER2611 PCN16266_ HTXA QFN7x7 & 5x5 CuPd wires - reliability evaluation plan.pdf 16266 _Additional information.pdf	

10. Affected parts		
10. 1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	STM32G071KBU6N	
	STM32G081CBU3	

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Public Products List

Public Products are off the shelf products. They are not dedicated to specific customers, they are available through ST Sales team, or Distributors, and visible on ST.com

PCN Title : HTXA (China) additional UFQFPN5x5 32L and UFQFPN7x7 48L package assembly line for STM32G03x/G04x, STM32G05x/G07x and STM32G08x listed products

PCN Reference : EMBEDDED PROCESSING/26/16266

Subject : Public Products List

Dear Customer,

Please find below the Standard Public Products List impacted by the change.

STM32G031K4U6TR	STM32G031K8U6TR	STM32G031K8U6
STM32G071CBU7TR	STM32G041K6U3TR	STM32G081KBU6
STM32G071KBU3	STM32G071K8U6	STM32G031K6U7
STM32G071C8U3TR	STM32G041K8U6	STM32G071KBU6N
STM32G041K6U3	STM32G031K4U3	STM32G081CBU3
STM32G071CBU7	STM32G071C8U7	STM32G071KBU6TR
STM32G071C8U3	STM32G031K8U7	STM32G071C8U7TR
STM32G031K8U7TR	STM32G031K4U6	STM32G071CBU3TR
STM32G071KBU7	STM32G071CBU6TR	STM32G031K6U6
STM32G071C8U6TR	STM32G071CBU3	STM32G071CBU6
STM32G031K8U3	STM32G081CBU3TR	STM32G071KBU6
STM32G031K8U3TR	STM32G081CBU6	STM32G031K4U3TR
STM32G071KBU3TR	STM32G071KBU7TR	

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PRODUCT/PROCESS CHANGE NOTIFICATION

PCN16266 – Additional information

HTXA (China) additional UFQFPN5x5 32L and UFQFPN7x7 48L package assembly line for STM32G03x/G04x, STM32G05x/G07x and STM32G08x listed products

MDRF – General Purpose and Automotive Microcontrollers (GPAM)

What are the changes?

Introduction of an additional assembly line to continue our path through the deployment of our Low-cost wire strategy to secure our supply chain.

Changes are described in table below:

Table 1

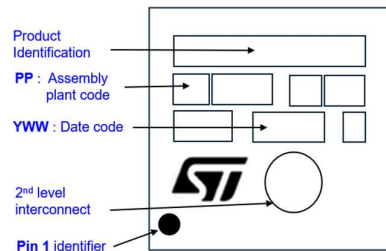
UFQFPN5x5 32L UFQFPN7x7 48L		Existing back-end assembly line				New assembly line
Assembly site		ST Calamba (Philippines)	ASE KaoHsiung (Taiwan)	StatsChipPAC JSCC Jiangyin (China)		HTXA (China)
Die Attach		LOCTITE ABLESTIK QMI519	EN4900G	Ablebond 8290	EN4900GC	
Molding compound ⁽¹⁾		9240ZHF10 W	Sumitomo EME-G631H	Sumitomo G770	Sumitomo G700LALA	Sumitomo G631BQ
Wire bonding		CuA 2N 0.8Mils	Gold 4N 0.8Mils	CuPd 0.8Mils	Gold 3N 0.8Mils	CuPd 0.8Mils
Lead frame		Copper, pre-plated	Copper, post-plated			
Leadfinishing ⁽²⁾		NiPdAu (e4)	PureTin (e3)			

(1) Package darkness might change depending on molding compound. Visual aspect (color) might change depending on substrate material. Marking position and size could be different upon assembly site, without any loss of information.

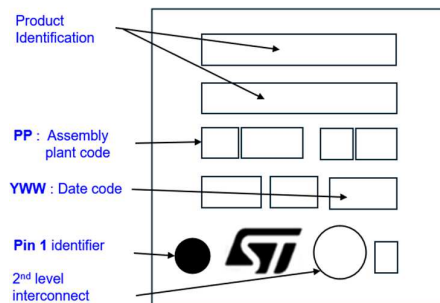
(2) Lead color and surface finish change depending on leadfinishing.

How can the change be seen?

The standard marking fields example below
for **UFQFPN 32L 5X5** package



for **UFQFPN 48L 7x7** package

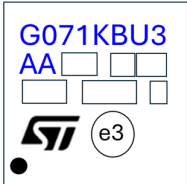
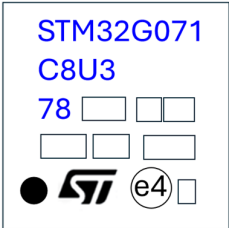


Pin1 identifier may change in terms of size and positioning however remaining near pin1's edge.
Marking position and size may be different upon assembly site, without any loss of information.

Table 2: Marking fields

	Existing Back-end			Added Back-End Site
Assembly sites	ST Calamba (Philippines)	ASE KaoHsiung (Taiwan)	StatsChipPAC JSCC Jiangyin (China)	HTXA (China)
PP : Assembly plant code	"78"	"AA"	"GQ"	"GU"

Table 3: Marking Example with Commercial product

Package example	ASE KaoHsiung (Taiwan)
UFQFPN 32L 5X5 (ie: STM32G071KBU3)	
UFQFPN 48L 7X7 (ie: STM32H742ZIT6)	

Please refer to product [DataSheet](#) or Technical Note **TN1433** for package marking details.

How to order samples?

For all samples request linked to this PCN, please:

- place a **Non-standard** sample order (choose Sample Non Std Type from pull down menu)
- insert the PCN number “**PCN16266**” into the NPO Electronic Sheet/**Regional Sheet**
- request sample(s) through Notice tool, indicating a single Commercial Product for each request

Partial Ship: 01 Price Pol: 05 Status: 01 Canc:

%: 0 Sample Type: Sample Non Std Type

Closing Type: Sample Std Type
Sample Non Std Type
Sample Non Std w Spl Tests

Lab Sheet:

SO | NPO Sample

Header

SO Nr: 8018502433 Customer: 99770200 01 ST-TOKYO SO Type: 30 Sample Order Cost Center: JT3129 SAMPLES /SALES J

PO Nr: Carrier Code: 0001 Price Policy: 05 Currency: 02 U.S. DOLLAR Req Name:

Notes: Status: 01 All items pending,ni Issuing Date: 25-JUN-2018 Ord Val: 0.0000 Sample Req Date: 25-Jun-2018

Sch I Nr	PO I. Nr.	Finished Good	Comm Qty	Open Qty	Plant Open Qty	Reqd Qty	Unit Price	RD	CD	EDD	St
1.1.10	000001	STM32F429NIH6	30	30	30	30	0.0000	25-Jun-18	01-Mar-59	01-Mar-59	01

Final Cust: PO Item: 000001 Comm Prod: STM32F429NIH6 Qty: 30 RD: 25-Jun-18 Unit Price: 0.0000 Final Cust: 8800367006 SANSHIN/NPC

Cust Part Nr: Finished Good: Partial Ship: 01 Price Pol: 05 Status: 01 Canc:

Notes: TAM K Pieces: 0 Our Share: 0 Sample Type: Sample Non Std Type

Project Name: Closing Date: Closing Type:

Regional Sheet:

Lab Sheet:

PCN 16266

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STRIVE
FOR EXCELLENCE

MDRF-GPAM-RER2611 PCN16266 HTXA UFQFPN 7x7 & 5x5 CuPd wire

Reliability Evaluation Plan

June 30th, 2026

MDRF GPAM Q&R

MDRF-GPAM-RER2611 PCN16266

HTXA UFQFPN 7x7 & 5x5 CuPd wire

Package Test Vehicles

Package line	Assembly Line	Package	Device (RawLine Code)	Diffusion Process/Plant	Number of Reliability Lots	Reliability
QFN	UFQFN32 5x5	32	MG*466	N90/TSMC	1	Full reliability
	UFQFN48 7x7	48	MI*460	N90/TSMC	2	Full reliability

Qualification strategy:

- HTXA UFQFN copper wire assembly line will be qualified with 3 package reliability lots from representative test vehicles of STM32G0x products:
 - 1 Full package reliability lot of UFQFN32 5x5 with N90 TSMC
 - 2 Full package reliability lot of UFQFN48 7x7 with N90 TSMC
- N90 TSMC technology will be qualified in HTXA for UFQFN32 5x5 and UFQFN48 7x7 package size
- Refer to details in above and next tables.

MDRF-GPAM-RER2611 PCN16266

HTXA UFQFPN 7x7 & 5x5 CuPd wire

Reliability plan

(*) tests performed after preconditioning

Reliability Trial & Standard		Test Conditions	Pass Criteria	Unit per Lot	Number of lot
PC	Pre Conditioning: Moisture Sensitivity Jedec Level 3 J-STD-020/ JESD22-A113	Bake (125°C / 24 hrs) Soak (30°C / 60% RH / 192 hrs) for level 3 Convection reflow: 3 passes	3 passes MSL3	231	3
Uhast(*)	UnBiased Highly Accelerated Temperature and Humidity Stress JESD22 A118	130°C, 85%RH, 2.3 atm	96h	77	3
TC(*)	Thermal Cycling JESD22 A104	-65°C +150°C	500cy	77	3
THB(*)	Biased temperature & humidity stress JESD22 A101	85°C, 85% RH bias	1000h	77	3
HTSL	High Temperature Storage Life JESD22 A103	150°C	1000h	77	3
Construction analysis	ST internal specification JESD 22B102 JESDB100/B108	Solderability, POA, Ball shear, pull test, IMC inspection , ST internal specification	NA	50	2
ESD	ESD Charge Device Model JEDEC JS-002	Aligned with datasheet	No failure	3	2

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